		ELANT	>		Comn	non Mode Choke
+	·	minun		0		•
	<ul> <li>SACT3225A Series Comr</li> <li>For high-speed differential general differential sign</li> </ul>	al signal line,	Filter	A HE		AEC-Q200 ROHS COMPLIANT
◆特征:			Features:			V
<ul> <li>绕线结构</li> <li>低损耗</li> <li>优异的可</li> <li>高频共构</li> </ul>	WHER .	游居科林	Excellent s	on loss at f olderability	requency rang	ge high frequencyeffects
7		e.	excellent n	oise suppre	ession perform	nance
0	HS,无卤和 REACH		100		and REACH C	Compliance
	:C-Q200.		• AEC-Q200			
◆ <b>用途:</b>	前及外设 USB 线		Application		computore en	nd peripheral
• IEEE 139	94 线用于个人电脑、DVC、S E晶面板线、图形卡等	TB	• IEEE 1394	line for per el line for li	quid display p	ia peripheral ers, DVC, STB banels, graph card etc
◆环境:	700. GrH	AL PEND	Environme	-	(FE)	
	€: -40℃ 至+150℃			· · · · · · · · · · · · · · · · · · ·	re: -40℃ to +	<b>150</b> ℃
(包括线圈	自身温升)		(Including o	coils self-te	mperature ris	e)
◆试验设	备:		Test Equip	ment:		18th FRO
● 阻抗:E4 ● 直流电阻	4284+42841A 991B+ HP16197A 测试夹具 1: Chroma 16502 或同等仪 239B 或同等仪器		<ul> <li>Isat &amp; Irms:</li> <li>Impedance</li> <li>DCR:Chror</li> <li>I.R:HP4239</li> </ul>	: E4991Ba na 16502 c	nalyzer with F or equivalent	IP16197A test fixture
◆产品型		und the	Product Ide			
SACI 1	2 <u>3225 A</u> 2 3	<u>501</u> ④	<u>2P</u> ⑤	I ©		
1	×Â. ]			<i>2</i> 0.,		)
SACT	类型 Type 贴片共模滤波器 SMD Common Mode Line Filter	Externa	尺寸(L×W×H) Il Dimensions (mm)			A
4		<u>322</u>	5 5.2	.2.2×2.5		6
Imp	edance	2P			包装P	acking
		Double Line	25			lk Package
	iluH				T 编带Ta	pe & Reel
<u>SHENZHEN</u>	LANTU MICRO ELECTRIC T	ECHNOLOGY CO	<u>., LTD.</u>		http:www.szlant	u.com.cn 1

		大国小批社	Common Mode Choke	
	◆外观尺寸:	Shape and Di	mensions(dimensions are in mm):	
>,		0 • • • • • • • • • • • • • • • • • • •	Recommended Land Pattern	
ſ		Schematic Diagram	THE PARTY	
			Λ	

Part No		~	ITEM	~	
	А	B	С	D1	D2
SACT3225A	3.3±0.2	2.5MAX	2.5±0.2	0.55±0.15	0.75±0.2
XXXX				X.Y.	

## ◆规格特性:

## Specifications:

• SACT3225A Series Electrical Characteristics (Electrical specifications at 25°C)

Part Number	Impe	on Mode dance (Ω)		Inductance(uH) +50/-30% [100kHz/0.1V]	DC Resistance (Ω) Max	Rated Current (mA) Max	Rated Voltage (Vdc) Max	Insulation Resistance (MΩ) Min
	Min	Тур		×			2	
SACT3225A-110-2P	300	550	10	11	0.4	300	80	10
SACT3225A-220-2P	500	1100	10	22	0.5	250	80	10
SACT3225A-510-2P	1000	2600	10	51	0.7	200	80	10
SACT3225A-101-2P	2200	5100	10	100	1.5	150	80	10

•Rated Current: the actual value of DC current when the temperature rise is $\Delta T$  40  $^{\circ}C$  (Ta=25 $^{\circ}C$ )

•Circuit: Test Mode







SHENZHEN LANTU MICRO ELECTRIC TECHNOLOGY CO., LTD.

X,







## Common Mode Choke

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Terminal Strength Reference documents: GB/T 2423.60-2008       Define: A: sectional area of terminal A ≤ 8mm2 force ≡ 50 k time: 10sec 23.60-2008       solder. Then apply a force in the Keep time: 10±1s Speed: 1.0mm/s.         2423.60-2008       200 mm2 <a 10sec<br="" 20="" force="" k="" time:="" ≡="">2.Solder paste thickness:0.12mm 3.Meet the above requirements without any loose terminal       Full Force:the force shall be applied gradua the terminal and thenmaintained for 10 sect 0.50 Applied force:5N Duration: 10sec3.Terminal diameter(d) mm0.50       Full Force:the force shall be applied gradua the terminal and thenmaintained for 10 sect 10sec3.Terminal diameter(d) mm0.80         2423.60-2008       1.25Applied force:20N Duration: 10sec4.Terminal diameter(d) mmD&gt; 1.25Applied force:20N Duration: 10sec5.Meet the above requirements without any loose terminal.       Full Force:the tenductor to the test jig (glass ef baard         1.No visible mechanical damage.       1. Solder the inductor to the test jig (glass ef baard       1. Solder the inductor to the test jig (glass ef baard         2. shown in Using a leadfree solder. Then af force in the direction shown 3. Flexure: 2mm.       1. Pressurizing Speed: 0.5mm/sec.         5. Keep time: 30 sec       5. Keep time: 30 sec       1. Pressurizing Speed: 0.5mm/sec.         5. Keep time: 30 sec       1. No visible mechanical damage.       1. Drop the packaged products from 1m high angle, 3 ridges and 6 surfaces, twice in each direction.         8 Filizity       1. No visible mechanical damage.       1. Solder temperture.240 ± 2°C 2. Duration: 3 sec.         5. GelfT 2423 28-2005       3. Solder: Shall ex</a>	tems	Requirements	Test Methods and Remarks
Terminal Strength Reference documents: GB/T 2423.60-2008       A ≤ 8mm2 force ≥ 6N time: 30sec 8mm2 <a 10sec<br="" 20mm2<a="" 20n="" force="" time:="" ≤="" ≥="">20mm2<a 10sec<br="" 20n="" force="" time:="" ≥="">2.Solder paste thickness: 0.12mm 3.Meet the above requirements without any loose terminal       Keep time: 10±15 Speed: 1.0mm/s.         Image: GMT       1.Terminal diameter(0) mm 0.35<d≤ 0.50Applied force: 5N Duration: 105ec2. Terminal diameter(0) mm0.50<d≤ 0.30Applied force: 10N Duration: 105ec3. Terminal diameter(0) mm0.80<d≤ 1.25Applied force: 40N Duration: 105ec5. Meet the above requirements without any loose terminal.       Pult Force:the force shall be applied gradue the terminal and thenmaintained for 10 sect 0.30Applied force: 40N Duration: 105ec5. Meet the above requirements without any loose terminal.         Image: GMT       1.No visible mechanical damage.       1.Solder the inductor to the test jig (glass et board 2.shown in Using a leadfree solder. Then applied force in the direction shown 3.Flexure: 2mm. 4.Pressurzing Speed: 0.5mm/sec. 5. Keep time: 30 sec         Dropping Reference documents: inappearance.       1.No visible mechanical damage. 2.No short and no open.       1.Drop the packaged products from 1m high angle, 3 ridges and 6surfaces, twice in each direction: 3 sec. 3. Flexing 5. Streng and 5. Surfaces, twice in each direction: 3 sec.</d≤ </d≤ </d≤ </a></a>		1. Pulling test:	Solder the inductor to the testing jig using leadf
A ≤ 8mm2 force ≤ 5N time: 30sec 8mm2 <a 10sec<br="" 20n="" 8mm2="" force="" time:="" ≤="" ≥="">2d23 60-2008 梁子強度(SMT) 2.Solder paste thickness:0.12mm 3.Meet the above requirements without any tosse terminal 1.Terminal diameter(d) mm0.35<d≤ 0.50 Applied force: 5N Duration: 10sec2.Terminal diameter(d) mm0.50<d≤ 0.50 Applied force: 10N Duration: 10sec3.Terminal diameter(d) mm0.80<d≤ 1.25 Applied force: 40N Duration: 10sec4.Terminal diameter(d) mm0.80<d≤ 1.25 Applied force: 40N Duration: 10sec4.Terminal diameter(d) mm0.80<d≤ 1.25 Applied force: 40N Duration: 10sec5.Meet the above requirements without any loose terminal. 1.No visible mechanical damage. 1.No visible mechanical damage. Dropping Reference documents: ampapearance. 2.No short and no open. ※ 下試驗 1.No visible mechanical damage. 2.No short and no open. ※ 下試驗 1.No visible mechanical damage. 1.Solder temperture: 240±2°C 2.Wetting shall exceed 75% coverage for 3.Terminals must have 95% minimum solders. 3. Solder: Sn/3.0Ag/0.5Ccu.</d≤ </d≤ </d≤ </d≤ </d≤ </a>	Forminal Otropath	Define: A: sectional area of terminal	solder. Then apply a force in the
ments: GB/T 2423.60-2008       Bmm2 <a 10n="" 10sec<br="" 220mm2="" force="" time:="" ≥="">20mm2<a 10sec<br="" 20n="" force="" time:="" ≥="">2. Solder paste thickness: 0.12mm 3. Meet the above requirements without any loose terminal       Pull Force:the force shall be applied gradue the terminal and thenmaintained for 10 sect 0.50Applied force:5N Duration: 10sec2. Terminal diameter(d) mm0.50 &lt; d 0.80Applied force:10N Duration: 10sec3. Terminal diameter(d) mm0.50 &lt; d 0.80Applied force:20N Duration: 10sec4. Terminal diameter(d) mm0.50 &lt; d 0.80Applied force:20N Duration: 10sec4. Terminal diameter(d) mm0.50 &lt; d 0.80Applied force:20N Duration: 10sec5. Meet the above requirements without any loose terminal.       Pull Force:the force shall be applied gradue the terminal and thenmaintained for 10 sect 0.80Applied force:20N Duration: 10sec5. Meet the above requirements without any loose terminal.         No visible mechanical damage.       1. Solder the inductor to the test jig (glass et board         List C 5321:1997 Årömtettime       1. No visible mechanical damage.       1. Solder the inductor to the test jig (glass et board         Dropping Reference documents: inappearance.       1. No visible mechanical damage.       1. Solder the packaged products from 1m high angle, 3 fidges and 6surfaces, twice in each direction.         Solder z423.72018 Solder z423.28-2005       1. No visible mechanical damage.       1. Solder temperture:240 ± 21°C 2. Duration: 3 sec.         Solder z423.28-2005       1. No visible mechanical damage.       1. Solder temperture:240 ± 21°C 2. Duration: 3 sec.</a></a>		A≦8mm2 force≧5N time:30sec	X
2423.60-2008       20mm2 <a 10sec<="" 20n="" force="" td="" time:="" ≥="">         2.Solder paste thickness:0.12mm       3.Meet the above requirements without any loose terminal         1.Terminal diameter(d) mm 0.35<d≤< td="">       Pult Force:the force shall be applied gradue the terminal and thenmaintained for 10 sect         0.50Applied force:IND Duration:       10sec2.Terminal diameter(d) mm0.80<d≤< td="">         1.25Applied force:20N Duration:       10sec4.Terminal diameter(d) mmD&gt;         1.25Applied force:40N Duration:       10sec5.Meet the above requirements         without any loose terminal.       1.No visible mechanical damage.       1.Solder the inductor to the test jig (glass et board         2.shown in Using a leadfree solder. Then af force in the direction shown       3.Flexure: 2mm.       4.Pressuring Speed: 0.5mm/sec.         Dropping       1.No visible mechanical damage.       1.Drop the packaged products from 1m higl         Reference documents:       1.No visible mechanical damage.       1.Solder temperture:240 ± 2°C         2.No short and no open.       1.Solder temperture:240 ± 2°C       2.Duration: 3 sec.         Solderability       1.No visible mechanical damage.       1.Solder temperture:240 ± 2°C         2.Newting shall exceed 75% coverage for       3.Solder: Sn/3.0Ag/0.5Cu.       4.Eur. 26W Debin ond 75% etheral in union</d≤<></d≤<></a>			
<ul> <li>第子強度(SMT)</li> <li>2.5 Older paste thickness:0.12mm</li> <li>3.Meet the above requirements without any loose terminal</li> <li>1.Terminal diameter(d) mm 0.35 <d≤< li=""> <li>0.50 Applied force:5N Duration:</li> <li>105ec2.Terminal diameter(d) mm0.50 <d≤< li=""> <li>0.80 Applied force:10N Duration:</li> <li>105ec2.Terminal diameter(d) mm0.80 <d≤< li=""> <li>1.25 Applied force:20N Duration:</li> <li>105ec4.Terminal diameter(d) mmD.</li> <li>1.25 Applied force:40N Duration:</li> <li>105ec5.Meet the above requirements without any loose terminal.</li> <li>1.No visible mechanical damage.</li> <li>1.No visible mechanical damage.</li> <li>1.Solder the inductor to the test jig (glass et board</li> <li>2.shown in Using a leadfree solder. Then af force in the direction shown</li> <li>3.Flexure: 2mm.</li> <li>4.Pressuring Speed: 0.5mm/sec.</li> <li>5.Keep time: 30 sec:</li> <li>1.No case deformation or change</li> <li>1.Drop the packaged products from 1m high angle, 3 ridges and 6surfaces, twice in each direction.</li> <li>2.No short and no open.</li> <li>Solder temperture: 240 ± 2.°C</li> <li>2.Wetting shall exceed 75% coverage for</li> <li>3.Terminals must have 95% minimum solder</li> <li>3.Solder: Sn/3.0Ag/0.5Cu.</li> </d≤<></li></d≤<></li></d≤<></li></ul>	(HE)	20mm2 <a 10sec<="" force="" td="" time:="" ≧20n=""><td>1 E CON</td></a>	1 E CON
3.Meet the above requirements without any loose terminal         1.Terminal diameter(d) mm 0.35 < d≤		2.Solder paste thickness:0.12mm	
erminal Strength Reference docu ments: GB/T 2423.60-2008 端子強度(DIP) 1. Terminal diameter(d) mm0.50 < d 0.80 Applied force: 5N Duration: 10sec3. Terminal diameter(d) mm0.50 < d 0.80 Applied force: 10N Duration: 10sec3. Terminal diameter(d) mm0.80 < d 1.25 Applied force: 20N Duration: 10sec4. Terminal diameter(d) mmD> 1.25 Applied force: 40N Duration: 10sec5. Meet the above requirements without any loose terminal. 1. No visible mechanical damage. I. No visible mechanical damage. I. No visible mechanical damage. Dropping Reference documents: GB/T 2423.7-2018 Solder ability Reference documents: GB/T 2423.28-2005 CB/T 2423.28-2005	而丁始度(SIVII)	3.Meet the above requirements without any	
erminal Strength Reference docu ments: GB/T 2423.60-2008 端子敏度(DIP)     0.50Applied force:5N Duration: 10sec2.Terminal diameter(d) mm0.50 < d≤ 0.80Applied force:10N Duration: 10sec3.Terminal diameter(d) mm0.80 < d≤ 1.25Applied force:20N Duration: 10sec5.Meet the above requirements without any loose terminal.     F Pulling test       Resistance to Flexure JIS C 5321:1997 抗弯曲性试验     1.No visible mechanical damage.     1.Solder the inductor to the test jig (glass er board       Dropping Reference documents: inappearance.     1.No case deformation or change inappearance.     1.Solder the packaged products from 1m higl angle, 3 ridges and 6surfaces, twice in each direction.       Dropping Reference documents: imappearance.     1.No visible mechanical damage.     1.Drop the packaged products from 1m higl angle, 3 ridges and 6surfaces, twice in each direction.       Solderability Reference documents: GB/T 2423.28-2005     1.No visible mechanical damage.     1.Solder temperture:240±2°C 2.Duration: 3 sec.       Solderability Reference documents: GB/T 2423.28-2005     1.No visible mechanical damage.     1.Solder temperture:240±2°C 2.Duration: 3 sec.		loose terminal	
erminal Strength Reference docu ments: GB/T 2423.60-2008 端子強度(DIP) Resistance to Flexure JIS C 5321:1997 抗弯曲性试驗 Dropping Reference documents: GB/T 2423.7-2018 Solderability Reference documents: BJI No visible mechanical damage. 1.No visible mechanical damage. 2.No short and no open. 1.Solder temperture; 240±2℃ 2.Duration: 3 sec. 3. Solder: Sn/3.0Ag/0.5Cu. 0.Vertane		1.Terminal diameter(d) mm 0.35 <d≤< td=""><td>Pull Force: the force shall be applied gradually t</td></d≤<>	Pull Force: the force shall be applied gradually t
erminal Strength Reference docu ments: GB/T 2423.60-2008 端子強度(DIP) 0.80Applied force:10N Duration: 10sec3.Terminal diameter(d) mmD> 1.25Applied force:20N Duration: 10sec4.Terminal diameter(d) mmD> 1.25Applied force:40N Duration: 10sec5.Meet the above requirements without any loose terminal. 1.No visible mechanical damage. JIS C 5321:1997 抗弯曲性试驗 Dropping Reference documents: arpearance. B/T 2423.7-2018 着下試驗 Solderability Reference documents: GB/T 2423.28-2005		0.50Applied force:5N Duration:	the terminal and thenmaintained for 10 second
Reference docu ments: GB/T 2423.60-2008 端子強度(DIP) Resistance to Flexure US C 5321:1997 抗弯曲性试驗 Dropping Reference documents: GB/T 2423.7-2018 Solderability Reference documents: GB/T 2423.28-2005 GB/T 2423.28-2005		10sec2.Terminal diameter(d) mm0.50 <d< td=""><td></td></d<>	
ments: GB/T       10sec3.3 Terminal diameter(d) mmD.80 <d≤< td="">         1.25Applied force:20N Duration:       1.25Applied force:40N Duration:         10sec4. Terminal diameter(d) mmD&gt;       1.25Applied force:40N Duration:         10sec5. Meet the above requirements       without any loose terminal.         1.No visible mechanical damage.       1.Solder the inductor to the test jig (glass et board         2.shown in Using a leadfree solder. Then an force in the direction shown       3.Flexure: 2mm.         JIS C 5321:1997       1.No case deformation or change       1.Drop the packaged products from 1m high angpearance.         Dropping       1.No sible mechanical damage.       1.Drop the packaged products from 1m high angpearance.         GB/T 2423.7-2018       1.No visible mechanical damage.       1.Solder temperture:240±2°C         Solderability       1.No visible mechanical damage.       1.Solder temperture:240±2°C         Wetting shall exceed 75% coverage for       3. Solder: Sn's 0.06/0.5Cu.         GB/T 2423.28-2005       3. Terminals must have 95% minimum solder       3. Solder: Sn's 0.06/0.5Cu.</d≤<>	•	0.80Applied force:10N Duration:	
2423.60-2008       1.25Applied force:20N Duration: 10sec4.Terminal diameter(d) mmD> 1.25Applied force:40N Duration: 10sec5.Meet the above requirements without any loose terminal.       1.Solder the inductor to the test jig (glass er board         Resistance to Flexure JIS C 5321:1997 抗弯曲性試驗       1.No visible mechanical damage.       1.Solder the inductor to the test jig (glass er board         Dropping Reference documents: GB/T 2423.7-2018       1.No case deformation or change inappearance.       1.Drop the packaged products from 1m higf angle, 3 ridges and 6surfaces, twice in each direction.         Solderability Reference documents: GB/T 2423.28-2005       1.No visible mechanical damage.       1.Solder temperture:240±2°C 2.Duration: 3 sec.		10sec3.Terminal diameter(d) mm0.80 <d≤< td=""><td>F</td></d≤<>	F
<ul> <li>開子強度(DP)</li> <li>10sec4. Terminal diameter(d) mmD&gt;</li> <li>1.25Applied force:40N Duration:</li> <li>10sec5.Meet the above requirements without any loose terminal.</li> <li>1.No visible mechanical damage.</li> <li>1.Solder the inductor to the test jig (glass en board</li> <li>2.shown in Using a leadfree solder. Then an force in the direction shown</li> <li>3.Flexure: 2mm.</li> <li>4.Pressurizing Speed: 0.5mm/sec.</li> <li>5.Keep time: 30 sec</li> <li>2.5No short and no open.</li> <li>7.No visible mechanical damage.</li> <li>2.No short and no open.</li> <li>7.No visible mechanical damage.</li> <li>2.No short and no open.</li> <li>7.No visible mechanical damage.</li> <li>2.No short and no open.</li> <li>7.No visible mechanical damage.</li> <li>2.No short and no open.</li> <li>7.No visible mechanical damage.</li> <li>2.Wetting shall exceed 75% coverage for</li> <li>3.Flexure: 2.002</li> <li>2.No short and no open.</li> <li>3. Fight 2423.28-2005</li> <li>3. Terminals must have 95% minimum solder:</li> <li>3. Solder: Sn/3.0Ag/0.5Cu.</li> <li>3. Solder: Sn/3.0Ag/0.5Cu.</li> </ul>		1.25Applied force:20N Duration:	
1.25Applied force:40N Duration: 10sec5.Meet the above requirements without any loose terminal.       1.Solder the inductor to the test jig (glass et board         Resistance to Flexure JIS C 5321:1997 抗弯曲性试验       1.No visible mechanical damage.       1.Solder the inductor to the test jig (glass et board         Dropping Reference documents: GB/T 2423.7-2018       1.No case deformation or change       1.Pressurizing Speed: 0.5mm/sec.         Solderability Reference documents: GB/T 2423.28-2005       1.No visible mechanical damage.       1.Drop the packaged products from 1m high angle, 3 ridges and 6surfaces, twice in each direction.         Solderability Reference documents: GB/T 2423.28-2005       1.No visible mechanical damage.       1.Solder temperture:240±2°C         2.Wetting shall exceed 75% coverage for 3.Terminals must have 95% minimum solder       1.Solder temperture:240±2°C		10sec4.Terminal diameter(d) mmD>	Pulling test
without any loose terminal.         1. No visible mechanical damage.         1. Solder the inductor to the test jig (glass epboard 2. shown in Using a leadfree solder. Then ap force in the direction shown 3. Flexure: 2mm.           JIS C 5321:1997 抗弯曲性试验         1. No visible mechanical damage.         1. Solder the inductor to the test jig (glass ep board           Dropping Reference documents: GB/T 2423.7-2018         1. No case deformation or change inappearance.         1. Drop the packaged products from 1m higi angle, 3 ridges and 6surfaces, twice in each direction.           Solderability Reference documents: GB/T 2423.28-2005         1. No visible mechanical damage.         1. Solder temperture:240±2°C 2. Duration: 3 sec.           1. No visible mechanical damage.         2. Vietting shall exceed 75% coverage for 3. Terminals must have 95% minimum solder         3. Solder: Sn/3.0Ag/0.5Cu.	而1 31反(日下)	1.25Applied force:40N Duration:	
1.No visible mechanical damage.       1.Solder the inductor to the test jig (glass epboard         Resistance to Flexure JIS C 5321:1997 抗弯曲性试验       1.No visible mechanical damage.       2.shown in Using a leadfree solder. Then apforce in the direction shown         J.Flexure: 2mm.       4.Pressurizing Speed: 0.5mm/sec.       5.Keep time: 30 sec.         Dropping       1.No case deformation or change inappearance.       1.Drop the packaged products from 1m high angle, 3 ridges and 6surfaces, twice in each direction.         B/T 2423.7-2018       1.No visible mechanical damage.       1.Solder temperture 240±2°C         Solderability Reference documents:       1.No visible mechanical damage.       1.Solder temperture 240±2°C         2.Wetting shall exceed 75% coverage for 3.Terminals must have 95% minimum solder       3.Solder: Sn/3.0Ag/0.5Cu.         4.Flow: 25% prise and 75% coverage for       3.Solder: Sn/3.0Ag/0.5Cu.		10sec5.Meet the above requirements	Line .
Resistance to Flexure JIS C 5321:1997 抗弯曲性试驗       1.No case deformation or change inappearance.       1.Drop the packaged products from 1m high angle, 3 ridges and 6surfaces, twice in each direction.         Dropping Reference documents: BB/T 2423.7-2018       1.No visible mechanical damage.       1.Solder temperture:240±2°C 2.Duration: 3 sec.         1.No visible mechanical damage.       1.Solder: Sn/3.0Ag/0.5Cu.       1.Solder: Sn/3.0Ag/0.5Cu.         2.Wetting shall exceed 75% coverage for 3.Terminals must have 95% minimum solder       1.Solder: Sn/3.0Ag/0.5Cu.		without any loose terminal.	
Resistance to Flexure JIS C 5321:1997 抗弯曲性试驗2.shown in Using a leadfree solder. Then a force in the direction shown 3.Flexure: 2mm. 4.Pressurizing Speed: 0.5mm/sec. 5.Keep time: 30 sec.Dropping Reference documents: GB/T 2423.7-20181.No case deformation or change inappearance. 2.No short and no open.1.Drop the packaged products from 1m high angle, 3 ridges and 6surfaces, twice in each direction.Solderability Reference documents: GB/T 2423.28-20051.No visible mechanical damage. 2.Wetting shall exceed 75% coverage for 3.Terminals must have 95% minimum solder GWT 2423.28-20051.Solder: Sn/3.0Ag/0.5Cu. 4.Etw: 26% Desin and 75% otherage in union		1.No visible mechanical damage.	1.Solder the inductor to the test jig (glass epoxy
Resistance to Flexure JIS C 5321:1997 抗弯曲性试验       force in the direction shown 3.Flexure: 2mm.         4.Pressurizing Speed: 0.5mm/sec.         5.Keep time: 30 sec         1.No case deformation or change         inappearance.         2.No short and no open.         Solderability Reference documents:         1.No visible mechanical damage.         2.Wetting shall exceed 75% coverage for 3.Terminals must have 95% minimum solder         BJT 2423.28-2005			board
Resistance to Flexure JIS C 5321:1997 抗弯曲性试验       3.Flexure: 2mm.         加容型型型型型型型型型型型型型型型型型型型型型型型型型型型型型型型型型型型型		x Ex	2.shown in Using a leadfree solder. Then apply
A.Pressurizing Speed: 0.5mm/sec. 5.Keep time: 30 sec. 4.Pressurizing Speed: 0.5mm/sec. 5.Keep time: 30 sec. 1.Drop the packaged products from 1m high angle, 3 ridges and 6surfaces, twice in each direction. 5.Keep time: 30 sec. 1.Drop the packaged products from 1m high angle, 3 ridges and 6surfaces, twice in each direction. 5.Keep time: 30 sec. 1.Drop the packaged products from 1m high angle, 3 ridges and 6surfaces, twice in each direction. 5.Keep time: 30 sec. 1.Drop the packaged products from 1m high angle, 3 ridges and 6surfaces, twice in each direction. 5.Keep time: 30 sec. 5.Keep time: 30 sec.		lin in	force in the direction shown
抗弯曲性试验 抗弯曲性试验 5.Keep time: 30 sec. 200 45[1.772]	Resistance to Flexure		3.Flexure: 2mm.
Dropping       1.No case deformation or change       1.Drop the packaged products from 1m high angle, 3 ridges and 6surfaces, twice in each direction.         BB/T 2423.7-2018       2.No short and no open.       1.Solder temperture:240±2°C         Solderability       2.Wetting shall exceed 75% coverage for 3.Terminals must have 95% minimum solder       1.Solder: Sn/3.0Ag/0.5Cu.         GB/T 2423.28-2005       1.Terminals must have 95% minimum solder       3.Solder: Sn/3.0Ag/0.5Cu.	JIS C 5321:1997		
Dropping       1.No case deformation or change       1.Drop the packaged products from 1m high angle, 3 ridges and 6surfaces, twice in each direction.         GB/T 2423.7-2018       2.No short and no open.       1.Drop the packaged products from 1m high angle, 3 ridges and 6surfaces, twice in each direction.         Solderability       1.No visible mechanical damage.       1.Solder temperture:240±2°C         Wetting shall exceed 75% coverage for       3.Terminals must have 95% minimum solder       3.Solder: Sn/3.0Ag/0.5Cu.         Overage       Coverage       4.Elux: 25% Paein and 75% otherapt in weight	<b>亢弯曲性试验</b>		5.Keep time: 30 sec.
Dropping       1.No case deformation or change       1.Drop the packaged products from 1m high angle, 3 ridges and 6surfaces, twice in each direction.         GB/T 2423.7-2018       2.No short and no open.       1.Drop the packaged products from 1m high angle, 3 ridges and 6surfaces, twice in each direction.         Solderability       1.No visible mechanical damage.       1.Solder temperture:240±2°C         Wetting shall exceed 75% coverage for       3.Terminals must have 95% minimum solder       3.Solder: Sn/3.0Ag/0.5Cu.         Overage       Coverage       4.Elux: 25% Paein and 75% otherapt in weight	E PENN	A BEAN	10
Dropping       1.No case deformation or change       1.Drop the packaged products from 1m high angle, 3 ridges and 6surfaces, twice in each direction.         GB/T 2423.7-2018       2.No short and no open.       1.Drop the packaged products from 1m high angle, 3 ridges and 6surfaces, twice in each direction.         Solderability       1.No visible mechanical damage.       1.Solder temperture:240±2°C         Wetting shall exceed 75% coverage for       3.Terminals must have 95% minimum solder       3.Solder: Sn/3.0Ag/0.5Cu.         Overage       Coverage       4.Elux: 25% Paein and 75% otherapt in weight		the t	R230
Dropping       1.No case deformation or change       1.Drop the packaged products from 1m high angle, 3 ridges and 6surfaces, twice in each direction.         GB/T 2423.7-2018       2.No short and no open.       1.Drop the packaged products from 1m high angle, 3 ridges and 6surfaces, twice in each direction.         Solderability       1.No visible mechanical damage.       1.Solder temperture:240±2°C         Wetting shall exceed 75% coverage for       3.Terminals must have 95% minimum solder       3.Solder: Sn/3.0Ag/0.5Cu.         GB/T 2423.28-2005       Coverage       4.Elux: 25% Pagin and 75% otherapt in weight	¥	~	Flowing
Dropping       1.No case deformation or change       1.Drop the packaged products from 1m high angle, 3 ridges and 6surfaces, twice in each direction.         GB/T 2423.7-2018       2.No short and no open.       1.Drop the packaged products from 1m high angle, 3 ridges and 6surfaces, twice in each direction.         Solderability       1.No visible mechanical damage.       1.Solder temperture:240±2°C         Solderability       2.Wetting shall exceed 75% coverage for       1.Solder: Sn/3.0Ag/0.5Cu.         GB/T 2423.28-2005       3.Terminals must have 95% minimum solder       3. Solder: Sn/3.0Ag/0.5Cu.		×2.	
Reference documents:       inappearance.         GB/T 2423.7-2018       angle, 3 ridges and 6surfaces, twice in each direction.         落下試驗       2.No short and no open.         Solderability       1.No visible mechanical damage.         Reference documents:       2.Wetting shall exceed 75% coverage for         GB/T 2423.28-2005       3.Terminals must have 95% minimum solder         GD/T 2423.28-2005       Coverage		with HO	
GB/T 2423.7-2018 落下試驗2.No short and no open.direction.Solderability Reference documents: GB/T 2423.28-20051.No visible mechanical damage. 2.Wetting shall exceed 75% coverage for 3.Terminals must have 95% minimum solder Coverage1.Solder temperture.240±2℃ 2.Duration: 3 sec. 3. Solder: Sn/3.0Ag/0.5Cu.	Dropping	1.No case deformation or change	1.Drop the packaged products from 1m high in
落下試驗 Solderability Reference documents: GB/T 2423.28-2005 I.No visible mechanical damage. 3.Terminals must have 95% minimum solder Coverage (Coverage) (	Reference documents:	inappearance.	angle, 3 ridges and 6surfaces, twice in each
Solderability       1.No visible mechanical damage.       1.Solder temperture:240±2℃         Reference documents:       2.Wetting shall exceed 75% coverage for       2.Duration: 3 sec.         GB/T 2423.28-2005       3.Terminals must have 95% minimum solder       3. Solder: Sn/3.0Ag/0.5Cu.	GB/T 2423.7-2018	2.No short and no open.	direction.
Solderability         Reference documents:         GB/T 2423.28-2005         Coverage         Coverage <td>客下試驗</td> <td><i>1</i>2.</td> <td></td>	客下試驗	<i>1</i> 2.	
Reference documents:       2.Wetting shall exceed 75% coverage for       2.Duration: 3 sec.         GB/T 2423.28-2005       3.Terminals must have 95% minimum solder       3. Solder: Sn/3.0Ag/0.5Cu.         Coverage       4. Elux: 25% Resin and 75% othered in weight	Solderability	1.No visible mechanical damage.	1.Solder temperture:240±2℃
GB/T 2423.28-2005 3.Terminals must have 95% minimum solder 3. Solder: Sn/3.0Ag/0.5Cu.	(FEX)	2.Wetting shall exceed 75% coverage for	2.Duration: 3 sec.
COVERAGE 4 Flux: 25% Design and 75% ethenel in weig		3. Terminals must have 95% minimum solder	3. Solder: Sn/3.0Ag/0.5Cu.
可焊性试验 4.Flux: 25% Resin and 75% ethanol in weig		coverage	4.Flux: 25% Resin and 75% ethanol in weight
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Items	Requirements	Test Methods and Remarks
	1.No visible mechanical damage.	1.Solder the inductor to the testing jig (glass epoxy
	2. Inductance change: Within ±10%.	boardshown in ) using leadfree solder.
	3.Q factor change: Within ±20%.	2.The inductor shall be subjected to a simple
A A A A A A A A A A A A A A A A A A A		harmonic motion having total amplitude of 1.5mm
1 King	Cupad Solder mask	the frequency being varied uniformly between the
A CALL STREET		approximate limits of 10 and 55 Hz.
Vibration		3.The frequency range from 10 to 55 Hz and
Reference documents:		return to 10 Hz shallbe traversed in approximately
GB/T 2423.10-2019	Glass Epoxy Board	1 minute. This motion shall be applied for a period
振動試验	A CONTRACTOR OF THE OWNER	of 2 hours in each 3mutually perpendicular
	ALL VEN	directions(total of 6 hours).
	1 till	Freq
		55Hz
	, white	
A KIN	E KINT	10Hz
	THE PERSON	0 1Min Time
	1.No visible mechanical damage.	1.Start at ( 85~125℃) for T time, rush to
	2. Inductance change: Within ±10%.(Mr	n-Zn: $(-55\sim40^\circ\!\!\mathrm{C})$ for T time as one cycle, go through100
	Within ≦30%)	cycles.
<del>.</del>	3.Q factor change: Within ±20%.	2. Transforming interval: Max. 20 sec
Thermal Shock		3.Tested cycle: 100 cycles.
Reference documents:	·	4. The chip shall be stabilized at normal condition
GB/T 2423.22-2012		for 1~2 hours
Method Na		125°C/85°C 30 min. 30 min.
冷热冲击试验	r Elli	Ambient
	The	Temperature 30 min.
Ÿ		-55°C/-40°C 20sec. (max.)
		AND
	1.No visible mechanical damage.	1.Temperature:M(-55~-40±2℃)
	2. Inductance change: Within ±10%.(Mn-Zn	2.Duration: 96±2 hours
Low temperature Storage	Within $\leq 30\%$ )	3. The chip shall be stabilized at normal condition for
Reference documents:	3.Q factor change: Within ±20%.	1~2 hoursbefore measuring.
GB/T 2423.1-2008	wh HE	Room ,
Method Ab	E GUE	Temp
低温储存试验		0 96H Test 97H 98H Time
· <b>P</b> ·	Ÿ.	MC
	*	Temp Low temperature
	white:	WA PE

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Items	Requirements	Test Methods and Remarks
High temperature Storage Reference documents: GB/T 2423.2-2008 Method Bb 高温储存试验	<ul> <li>1.No visible mechanical damage.</li> <li>2. Inductance change: Within ±10%.(Mn-Zn: Within ≤ 30%)</li> <li>3.Q factor change: Within ±20%.</li> </ul>	3. The chip shall be stabilized at normal condition for 1~2 hoursbefore measuring. Temp N°C Room Temp Test
Damp Heat	1.No visible mechanical damage. 2. Inductance change: Within $\pm 10\%$ .(Mn-Zn: Within $\leq 30\%$ )	3.Duration: 96±2 hours.
(Steady States) Reference documents: GB/T 2423.3-2016 恒定湿热试验	3.Q factor change: Within ±20%.	4. The chip shall be stabilized at normal condition for 1~2 hoursbefore measuring. Temp 4 Humidity 93% RH Room Conditions 0 96H 97H 98H Time
Heat endurance of Reflow soldering Reference documents: GJB 360B-2009 回流焊耐热性试验	1.No significant defects in appearance. 2. $\triangle$ L/L $\leq$ 10% (Mn-Zn: $\triangle$ L/L $\leq$ 30% ) 3. $\triangle$ Q/Q $\leq$ 30% (SMD series only) 4. $\triangle$ DCR/DCR $\leq$ 10%	1.Refer to the above reflow curve and go throug the reflow for twice. 2.The peak temperature : 260+0/-5℃
Resistance to solvent test Reference documents: IEC 68-2-45:1993 耐溶剂性试验	No case deformation or change in appearance or obliteration of marking	To dip parts into IPA solvent for 5±0.5Min,then drying them at room temp for 5Min,at last ,to brushing making 10 times.
Overload test Reference documents: JIS C5311-6.13 过负荷试验	1.During the test no smoke, no peculiar, smell, no fire 2.The characteristic is normal after test	Apply twice as rated current for 5 minutes.
voltage resistance test Reference documents: MIL-STD-202G Method 301	1.During the test no breakdown 2.The characteristic is normal after test	<ol> <li>For parts with two coils</li> <li>DC1000V, Current: 1mA, Time: 1Min.</li> <li>Refer to catalogue of specific products</li> </ol>

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The recommended reflow conditions as above graph, is set according to our soldering equipment. DUE to various manufactures may have different reflow soldering equipment, products, process conditions, set methods. And so on, when setting the reflow conditions, Please adjust and confirm according to users' environment/equipment.

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**TECHNOLOGY CO.** 

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## 使用注意事项 REMINDERS FOR USING THESE PRODUCTS

• 保存时间为12 个月以内,保存条件(温度5~40°C以下、湿度35 ~ 66%RH 以下),需充分注意。 若超过保存时间,端子电极的可焊性将可能老化。

The storage period is within 12 months. Be sure to follow the storage conditions (temperature: 5~40°C, humidity: 35 to 65% RH or less). If the storage period elapses, the soldering of the terminal electrodes may deteriorate.

- 请勿在气体腐蚀环境(盐、酸、碱等)下使用和保存。
   Do not use or store in locations where there are conditions such as gas corrosion (salt, acid, alkali, etc.).
- 手上的油脂会导致可焊性降低,应避免用手直接接触端子。
- Don't touch electrodes directly with bare hands as oil secretions may inhibit soldering Always ensure optimum conditions for soldering.
- 请小心轻拿轻放,避免由于产品的跌落或取出不当而导致的损坏

Please always handle products carefully to prevent any damage caused bydropping down or inappropriate removing.

- 端子过度弯曲会导致断线,请不要过度弯曲端子。
   Don't bend the terminals with excessive stress in case of any wire fracture。
- 不要清洗产品,如需要清洗时请联系我司。
   Don't rinse coils by yourself and please contact SXN if necessary。
- 请勿将本产品靠近磁铁或带有磁力的物体

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Don't expose the products to magnets or magnetic fields

- 在实施焊接前,请务必进行预热。预热温度与焊接温度及芯片温度的温度差要在150°C 以内。
   Before soldering, be sure to preheat components. The preheating temperature should be set so that the temperature difference between the solder temperature and chip temperature does not exceed 150°C.
- 安装后的焊接修正应在规格书规定的条件范围内。若加热过度可能导致短路、性能降低、寿命减少。
   Soldering corrections after mounting should be within the range of the conditions determined in the specifications. If overheated, a short circuit, performance deterioration, or lifespan shortening may occur.
- 装置会因通电而自我发热(温度上升),因此在热设计方面需留有充分余地。
   Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
- 非磁屏蔽型在基板设计时需注意配置线圈,受到电磁干扰可能会导致误动作。
   Carefully lay out the coil for the circuit board design of the non-magnetic shield type. A malfunction may occur due to magnetic interference.